

PATENT ASSIGNMENT

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SUBMISSION TYPE:

NEW ASSIGNMENT

APPLICATION NUMBER

11/163849

NATURE OF CONVEYANCE:

ASSIGNMENT OF ASSIGNOR'S INTEREST

CONVEYING PARTY DATA

Name	Execution Date
Cheng-Kuen Chen	2005-10-29
Chih-Ning Wu	2005-10-29
Wei-Tsun Shiau	2005-10-29
Wen-Fu Yu	2005-10-29

RECEIVING PARTY DATA

Name	Street Address	Internal Address	City	State/Country	Postal Code
UNITED MICROELECTRONICS CORP.	No.3, Li-Hsin Road 2, Science-Based Industrial Park		Hsin-Chu City	TAIWAN	

CORRESPONDENCE DATA

FAX NUMBER: 8064986673

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.

CUSTOMER NUMBER: 027765

NAME OF PERSON SIGNING:

WINSTON HSU

DATE SIGNED:

2005-10-31

Total Attachments: 2

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CH \$40.00 503105 11163849

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Cheng-Kuen Chen Nationality: R.O.C.
Address: 4F, No. 3, Aly. 30, Lane 279, Sec. 1, Fuhsing S. Rd., Taipei City, Taiwan, R.O.C.

Name: Chih-Ning Wu Nationality: R.O.C.
Address: 8F-6, No. 30, Lane 459, Sec. 1, Kuang-Fu Rd., Hsin-Chu City, Taiwan, R.O.C.

Name: Wei-Tsun Shiau Nationality: R.O.C.
Address: No. 19, Wen-Hua St., Long-Shan Li, Mei-Nong Town, Kao-Hsiung Hsien, Taiwan, R.O.C.

Name: Wen-Fu Yu Nationality: R.O.C.
Address: 7F-1, No. 130, Chinzhu Rd., Hsin-Chu City, Taiwan, R.O.C.

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: UNITED MICROELECTRONICS CORP.
Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"Method of removing a metal silicide layer on a gate electrode in a semiconductor manufacturing process and etching method"

Which is found in :

- (a) + U.S. patent application executed on even date
(b) _____ U.S. patent application executed on _____
(c) _____ U.S. application serial no. _____
(d) _____ patent no. _____ issued _____

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

OCT. 29 2005

IN WITNESS WHEREOF, We have hereunto set hand and seal this _____ (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Cheng-Kuen ChenCheng Kuen ChenChih-Ning WuChih Ning WuWei-Tsun ShiauWei Tsun ShiauWen-Fu YuWen-Fu Yu